



Kapton Polyimide Tape Specifications

Doc V: 1.0



Technical Data:

	Units	Value	Test method
Backing Thickness:	mm	0.025	
Total Tape Thickness:	mm	0.060	
Adhesion to Steel:	N/cm	1.4	GB-T2972
Tensile Strength at Break:	N/cm	58	GB-T7753
Elongation at Break:	%	60	GB-T7753
Upmost use Temperature:	°C	260	
Surface Resistance:	ohms	10 ⁶⁻⁸	
Static Charge:	Removal from roll:	V	<100
	From SUS:	V	<50
Dielectric Strength:	volts	4000	GB/T7752-87
Thermal Conductivity:	W/m.K	≥0.12	

Applications:

PCB Masking, High Temperature Clamping, Keypad and Membrane Switch Applications, Surface Protection, Splicing of Silicone Papers and Films, Powder Coating Masking and Electroplating.

Features:

Employs a proprietary technology that results in extremely low electrostatic discharge at unwind and removal from SUS. Conventional polyimide tape typically generate over 10,000 volts during use which can damage electronic components. The low static properties of our Kapton Tape can eliminate circuit board degradation.

Storage Environment:

Store under normal conditions of 10°C. to 30°C. and 40 to 70% relative humidity in the original packaging.

Size:

Width available from 4mm-300mm x 33m. Please contact us if you have a custom width requirement.

